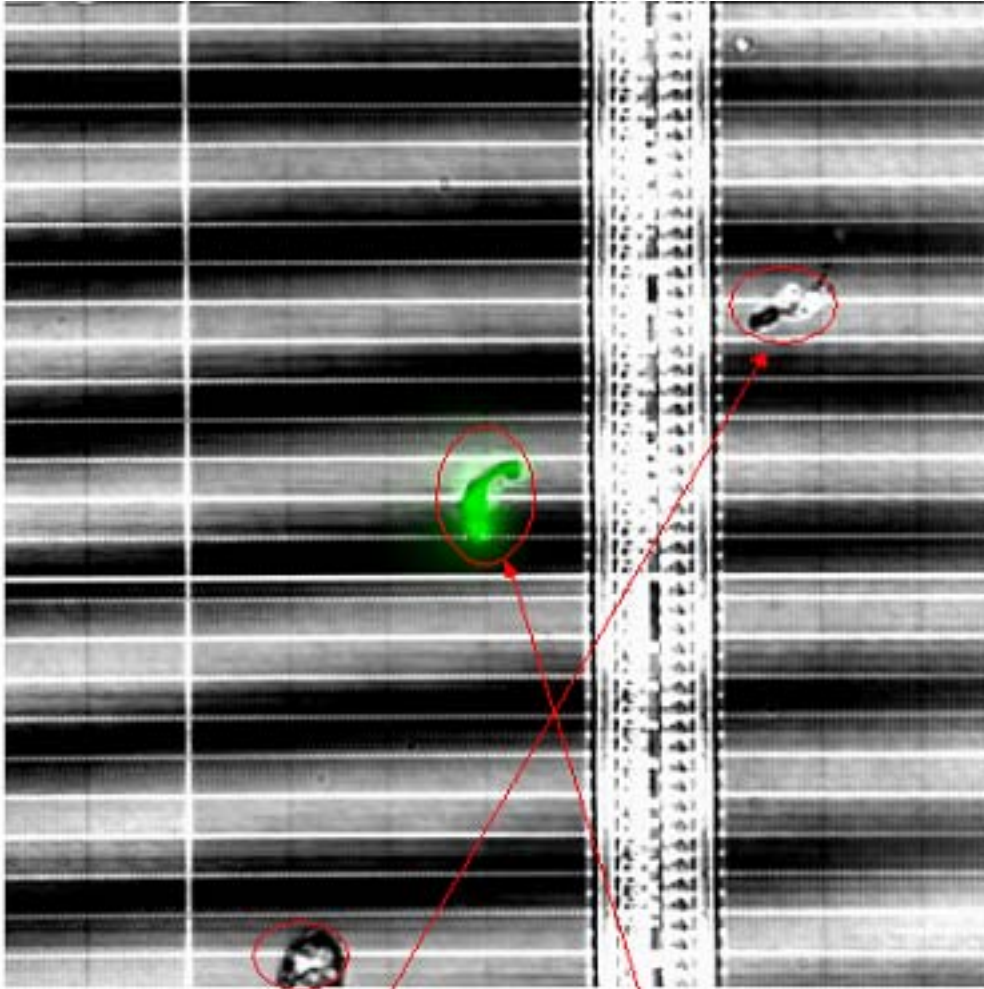


Low Resistance TIVA

Backside Die-level



Backside TIVA image of particle-induced non-planar dual damascene failure. Vcc to Vss resistance was $\sim 5 \Omega$. Images and data obtained with the Infrascan 200.

CHECKPOINT

TECHNOLOGIES, LLC

Locating Failures in IC Devices™

66 Bonaventura Dr., San Jose, CA 95134

Tel. 408-321-9780; E-mail: Sales@checkpointtechnologies.com